PATENT ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	SECURITY AGREEMENT

CONVEYING PARTY DATA

Name	Execution Date
Semicoa Corporation, a Delaware corporation	03/01/2011

RECEIVING PARTY DATA

Name:	Comerica Bank, a Texas banking association
Street Address:	39200 Six Mile Road
Internal Address:	National Documentation Services
City:	Livonia
State/Country:	MICHIGAN
Postal Code:	48152

PROPERTY NUMBERS Total: 5

Property Type	Number
Patent Number:	6103584
Patent Number:	6020745
Patent Number:	5798652
Patent Number:	5387805
Patent Number:	5334874

OP $200.00 6103584

CORRESPONDENCE DATA

Fax Number: (734)930-2494
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.
Phone: 734-761-3780
Email: asujek@bodmanlaw.com
Correspondent Name: Angela Alvarez Sujek - Bodman PLC
Address Line 1: 201 South Division, Ste. 400
Address Line 4: Ann Arbor, MICHIGAN 48104

NAME OF SUBMITTER:	Angela Alvarez Sujek

Total Attachments: 5
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INTELLECTUAL PROPERTY SECURITY AGREEMENT
(SEMICOA CORPORATION)

This Intellectual Property Security Agreement (this "Agreement") is entered into as of March 1, 2011, by and between COMERICA BANK ("Bank") and SEMICOA CORPORATION, a Delaware corporation ("Grantor").

RECITALS

A. Bank has agreed to make certain advances of money and to extend certain financial accommodation to Semicoa Holdings, Inc., a Delaware corporation ("Co-Borrower") and Grantor (the "Loans") in the amounts and manner set forth in that certain Loan and Security Agreement by and among Bank, Co-Borrower and Grantor dated of even date herewith (as the same may be amended, modified or supplemented from time to time, the "Loan Agreement"). Capitalized terms used herein are used as defined in the Loan Agreement.

B. Bank is willing to make the Loans to Grantor and Co-Borrower, but only upon the condition, among others, that Grantor shall grant to Bank a security interest in certain Copyrights, Trademarks and Patents to secure the Obligations.

C. Pursuant to the terms of the Loan Agreement, Grantor has granted to Bank a security interest in all of Grantor's right, title and interest, whether presently existing or hereafter acquired, in, to and under all of the Collateral.

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, and intending to be legally bound, as collateral security for the prompt and complete payment when due of the Obligations, Grantor hereby represents, warrants, covenants and agrees as follows:

AGREEMENT

To secure the Obligations, Grantor grants and pledges to Bank a security interest in all of Grantor's right, title and interest in, to and under its Intellectual Property Collateral (including without limitation those Copyrights, Patents and Trademarks listed on Exhibits A, B and C hereto), and including without limitation all proceeds thereof (such as, by way of example but not by way of limitation, license royalties and proceeds of infringement suits), the right to sue for past, present and future infringements, all rights corresponding thereto throughout the world and all re-issues, divisions continuations, renewals, extensions and continuations-in-part thereof. Notwithstanding anything contained in this Intellectual Property Security Agreement to the contrary, the collateral granted hereunder shall not include anything that is not "Intellectual Property Collateral" under, and as defined in, the Loan Agreement.

The security interest granted hereunder is granted in conjunction with the security interest granted to Bank under the Loan Agreement. The rights and remedies of Bank with respect to the security interest granted hereby are in addition to those set forth in the Loan Agreement and the other Loan Documents, and those which are now or hereafter available to Bank as a matter of law or equity. Each right, power and remedy of Bank provided for herein or in the Loan Agreement or any of the Loan Documents, or now or hereafter existing at law or in equity shall be cumulative and concurrent and shall be in addition to every right, power or remedy provided for herein and the exercise by Bank of any one or more of the rights, powers or remedies provided for in this Intellectual Property Security Agreement, the Loan Agreement or any of the other Loan Documents, or now or hereafter existing at law or in equity, shall not preclude the simultaneous or later exercise by any person, including Bank, of any or all other rights, powers or remedies.

Grantor represents and warrants that Exhibits A, B, and C attached hereto set forth any and all Copyrights, Patents, and Trademarks which Grantor owns and has registered or filed an application with either the United States Patent and Trademark Office or the United States Copyright Office, as applicable.

IN WITNESS WHEREOF, the parties have caused this Intellectual Property Security Agreement to be duly executed by its officers thereunto duly authorized as of the first date written above.

GRANTOR:

Address of Grantor:

333 McCormick Avenue
Costa Mesa, CA 92626
Phone: (714) 979-1900
Fax: (714) 557-4541

SEMICOA CORPORATION

By: ______________________

Its: CFO

BANK:

Address of Bank:

Comerica Bank
Attn: National Documentation Services
39200 Six Mile Road
Mail Code 7578
Livonia, MI 48152

COMERICA BANK

By: ______________________

Its: VP

EXHIBIT A

Copyrights

None.

EXHIBIT B

Patents

Title	App. No.	Filing Date	Reg. No.	Date Granted
Uniform current density and high current gain bipolar transistor	09/300169	4/27/99	6,103,584	8/15/00
Method of batch testing surface mount device using a substrate edge connector	08/796127	2/6/97	6,020,745	2/1/00
Method of batch testing surface mount devices using a substrate edge connector	08/688234	7/29/96	5,798,652	8/25/98
Field controlled thyristor	08/177686	1/5/94	5,387,805	2/7/95
Electronic device package	07/759165	9/13/91	5,334,874	8/2/94

EXHIBIT C

Trademarks

Mark	App. No.	Filing Date	Reg. No.	Reg. Date
SEMICOA	72/367666	8/10/70	974,285	12/4/73